

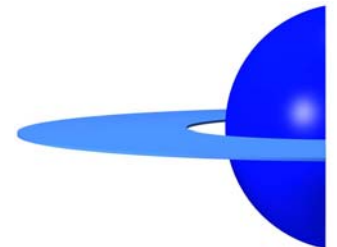
Micro/Nano Probes Enabling Next Generation Space Exploration

Fredrik Bruhn, Johan Köhler, Lars Stenmark

4th Round Table on Micro/Nano Technologies for Space

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fredrik.bruhn@angstrom.uu.se



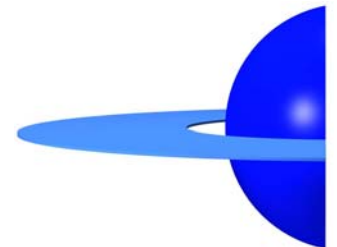
Outline

- Summary
- NanoSpace – The MMS road from airbrush to flight
 - ◆ Earth Intelligence Surveillance (E.I.S.) satellite concept
 - ◆ EIS Design
- MMS enabling interplanetary endeavors
 - ◆ Micro Autonomous Underwater Vehicle AUV
 - ◆ Inflatable Spherical Micro Rover/Robot
 - ◆ Inflatable Venusian Balloon (LOVECraft)
- How much electronics and mechanical functions can a MMS hold?

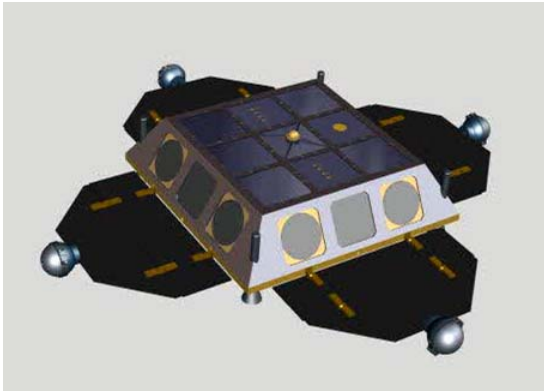


Summary

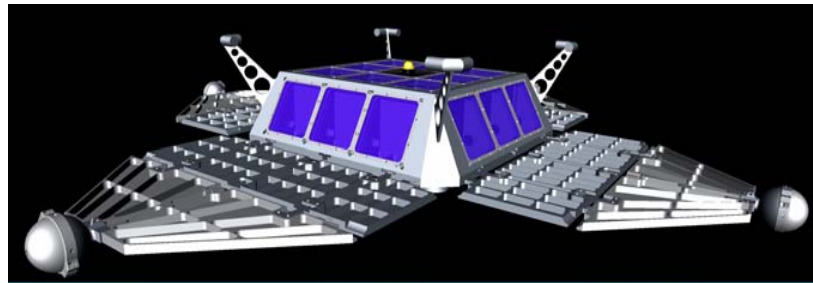
- Light-weight high-performing Micro/Nano Probes/Spacecraft are really feasible
- Enabling parallel exploration of the planetary system to a moderate cost
- Enables cluster exploration of a planetary body surface
- Much higher percentages of payload possible, i.e. more multifunctional components that are not just dead weight.



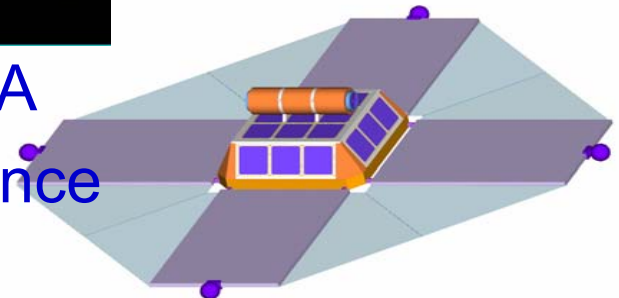
NanoSpace – The MMS road from airbrush to flight



- Currently part of SNSB Phase-A study (TechoSat)
- MMS designed platform
- General modules => Direct spin-offs to new applications



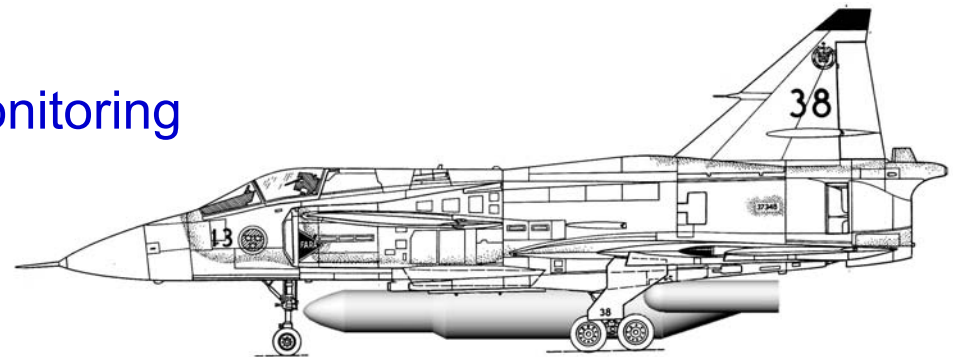
- Well defined processes and QA/PA
- Valuable lessons learned, experience on system level integration of complex MEMS modules



Earth Intelligence Surveillance (E.I.S.)



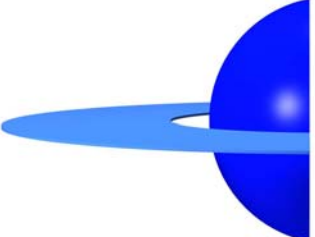
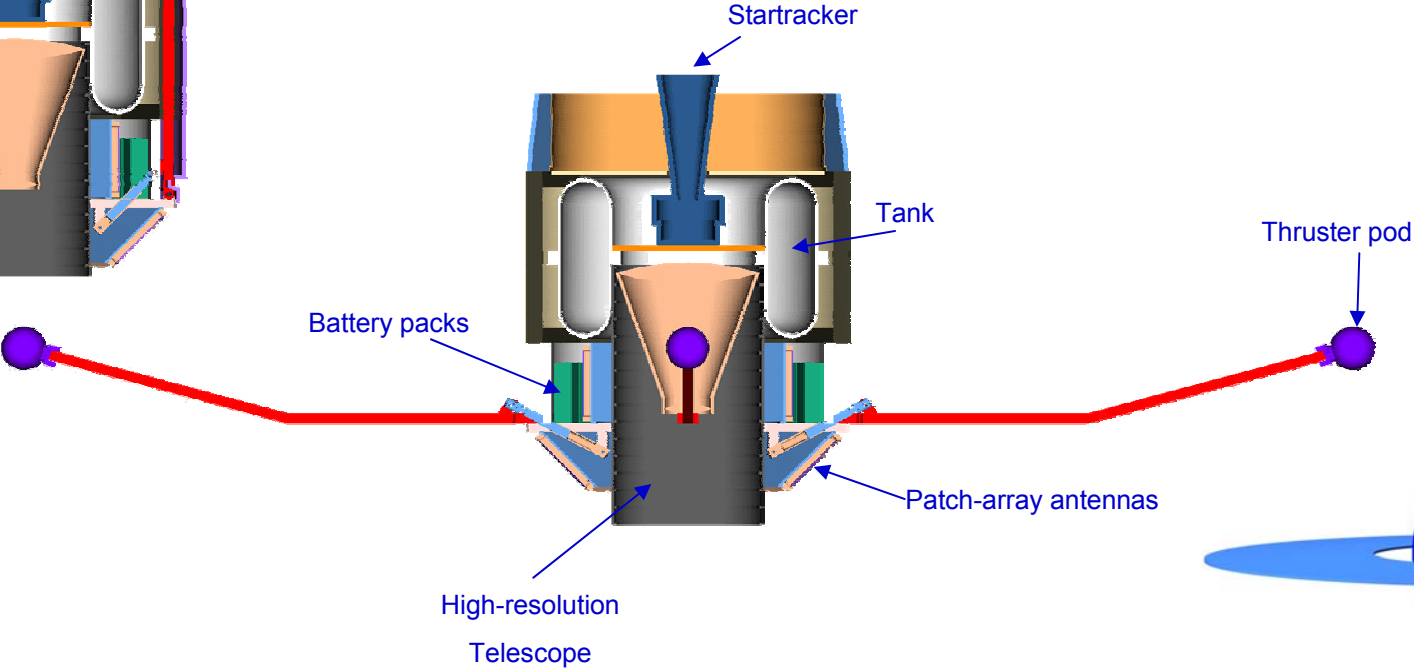
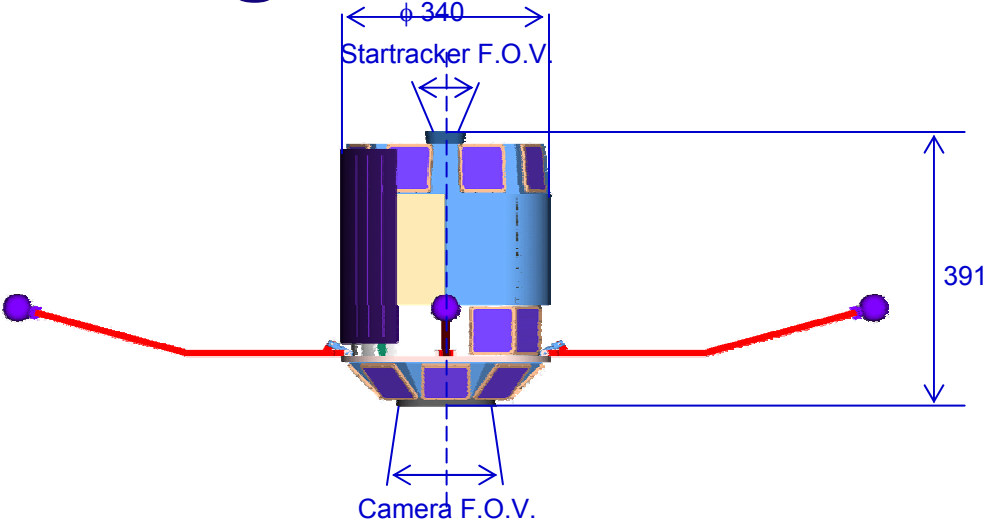
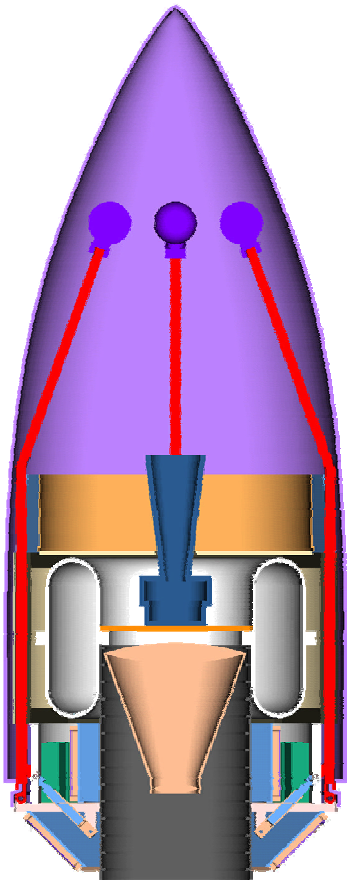
- Sponsored by the Swedish Defense
- First satellite based on MMS for customer demand
- Applications are both Military and Civilian,
 - ◆ Visual monitoring (3m-ground resolution)
 - ☞ Natural disasters
 - ☞ Criminal activities
 - ☞ International conflict monitoring
 - ☞ Military intelligence
 - ◆ Radio/Signal monitoring



- Top requirement: The E.I.S. system shall be deployable with a fighter jet

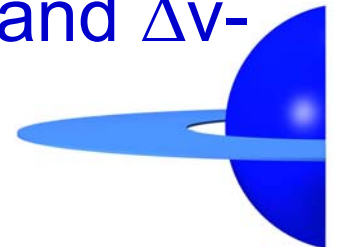


EIS - Design



MMS enabling interplanetary endeavors

- Reduction of size and mass of electronics
 - ◆ Increased performance / weight, such as autonomy, distributed systems, artificial intelligence, neural networks, scientific computing, re-configurable electronics
- Reduction of interconnections, wiring between mechanical functions, inertial navigation components
- High performing modules can be used in different missions with software updates
- Less overall weight, thus reducing costs and Δv -requirements



Micro Autonomous Underwater Vehicle AUV for Europa



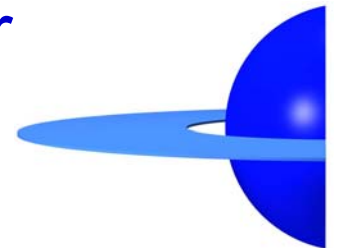
In collaboration with NASA/Jet Propulsion Laboratory



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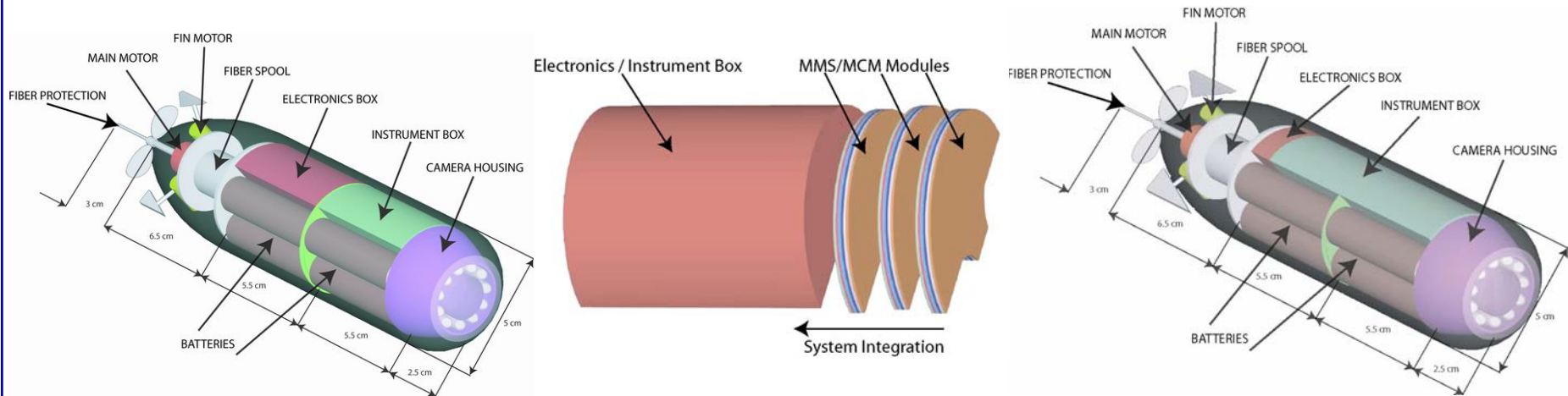
Micro AUV – Requirements

- Have maximum size of;
Diameter: 8cm, Length 30cm
- The AUV shall measure Conductivity, Temperature, and Depth (CTD) and at least accommodate two other instruments
- The AUV shall have a high-resolution camera
- The AUV shall be deployable from other dimensionally constrained host vehicles for operation in naturally occurring sites characterized by small size and acidic or alkaline water.

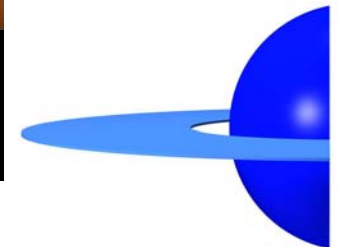


Micro AUV – MMS design benefits

- Optical Fiber Transceiver, 100s of meters to km of onboard spooled optical fiber
- Electronic compacted in size and mass by 10-15 times
- Allowing high power densities
- System Electronics and navigation packed in three modules; Weight: ~ 100g
- Internally distributed intelligence over I²C bus

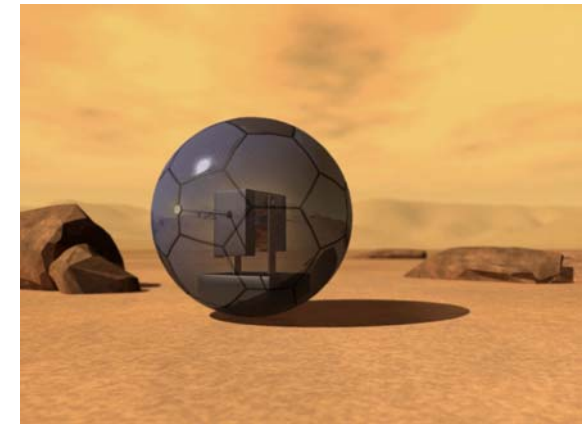


SMIPS – Autonomous Inflatable Micro Rover/Robot for Planetary Exploration



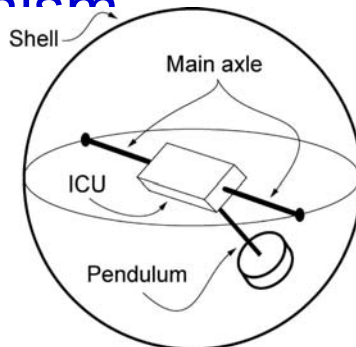
SMIPS – Design Goals

- Total weight of 3.5-4kg for deployment on Mars
- Minimize the weight of electronics and instrumentation
- Batteries and DC-motors shall have a large % of the total mass and be positioned as far down on the pendulum as possible

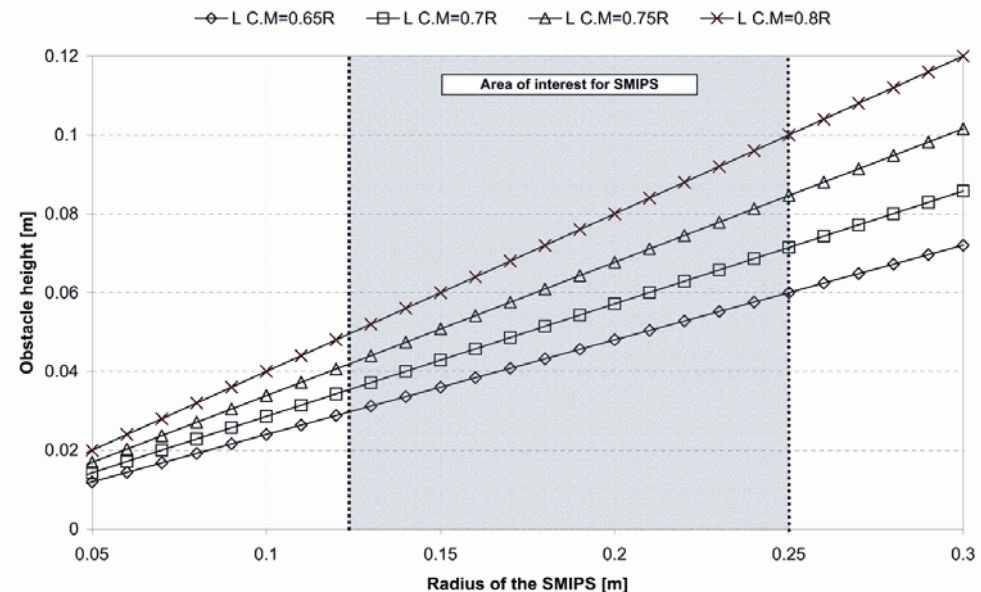


=> higher L_{cm}

- Jump Mechanism

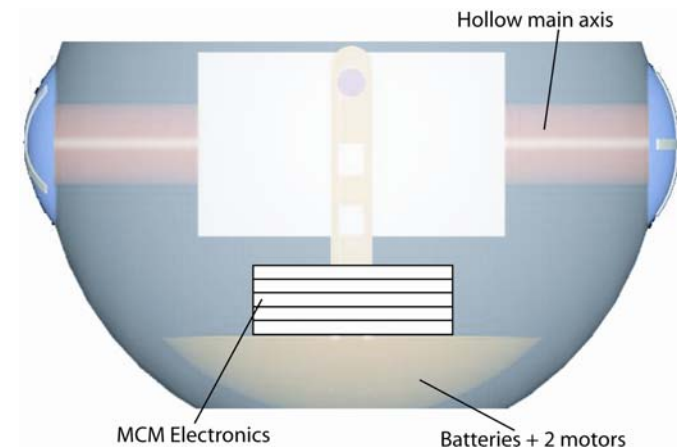
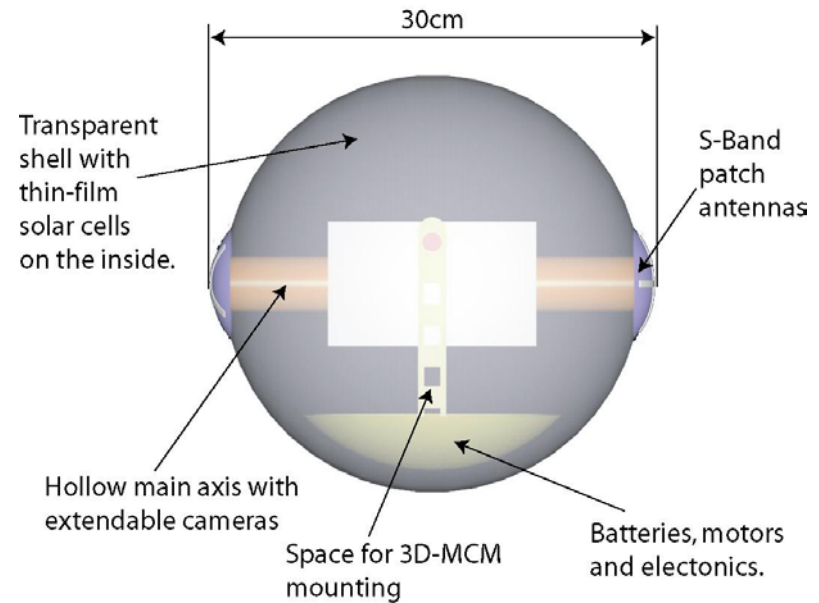


Maximum height of the obstacle that can be overrun without initial velocity

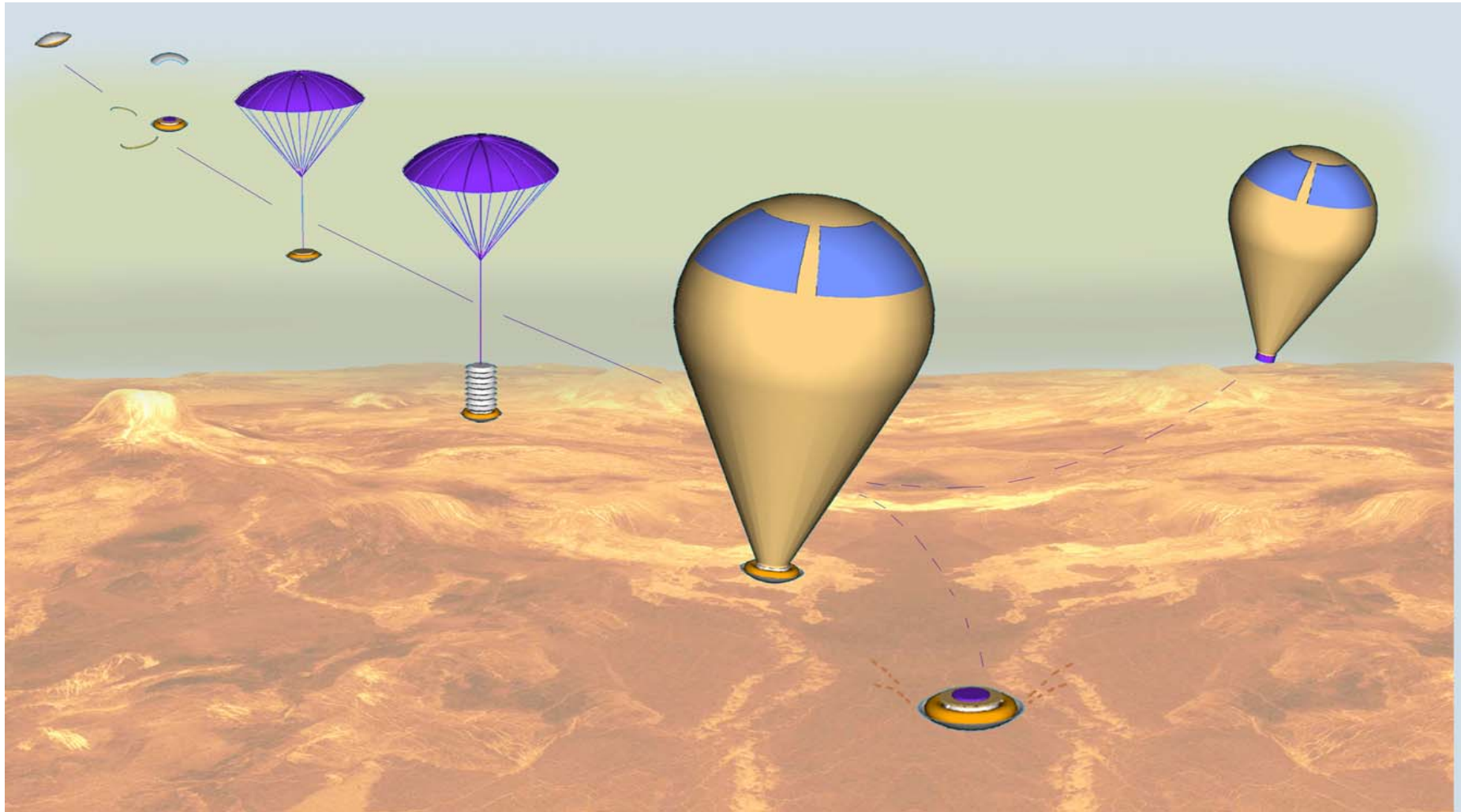


SMIPS – MMS design benefits

- High L_{cm} ratio, 0.75R is expected
- Thin film solar cells
- S-band patch antennas
- MCM-packed electronics
- Sun sensors, cameras, accelerometers, gyros

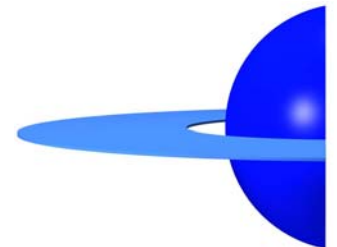


Venus Exploration – LOVECRAFT

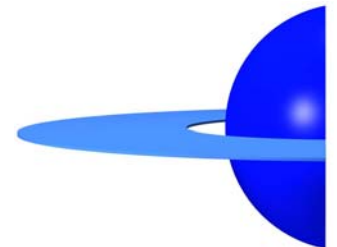
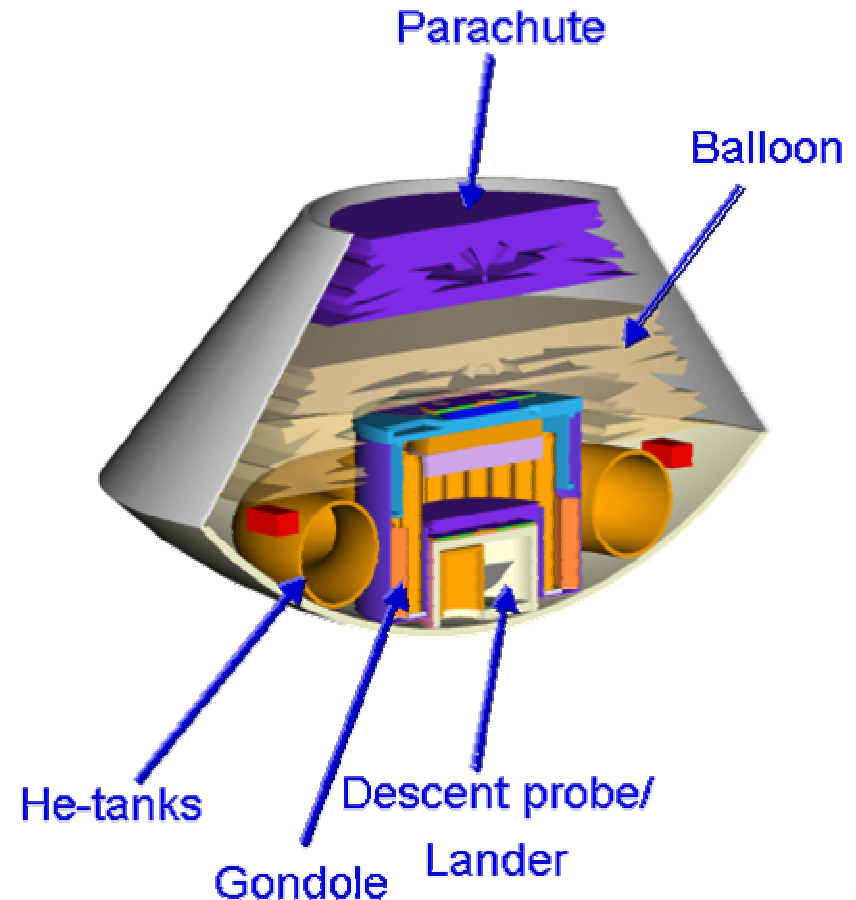
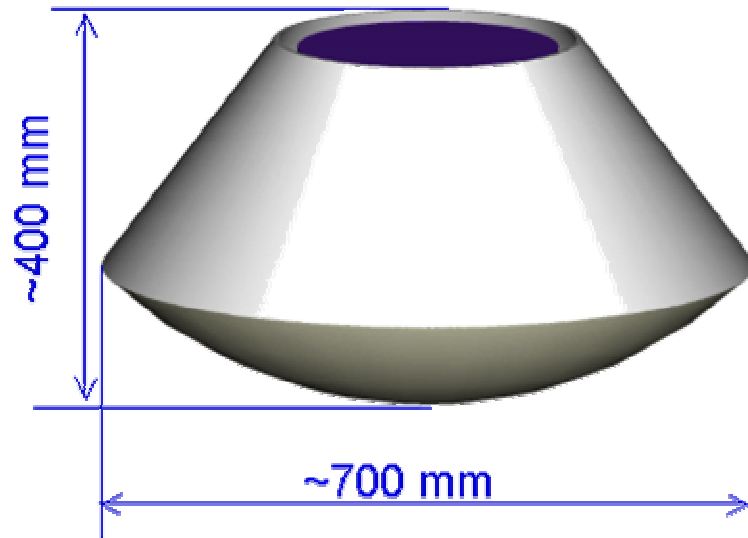


LOVECraft – MMS Implementation

- Total weight: < 30kg
- Multifunctional ballast probes
 - ◆ Count: 20 probes
 - ◆ Weight: 100g/each
 - ◆ Each ballast probe includes scientific instrumentation, a small breaking balloon, radio transmitter
- CIGS Thin-film solar cells
- 3D-MCM Modules
- Phased Array antenna
- Micro Cold Gas Thrusters, de-spinning

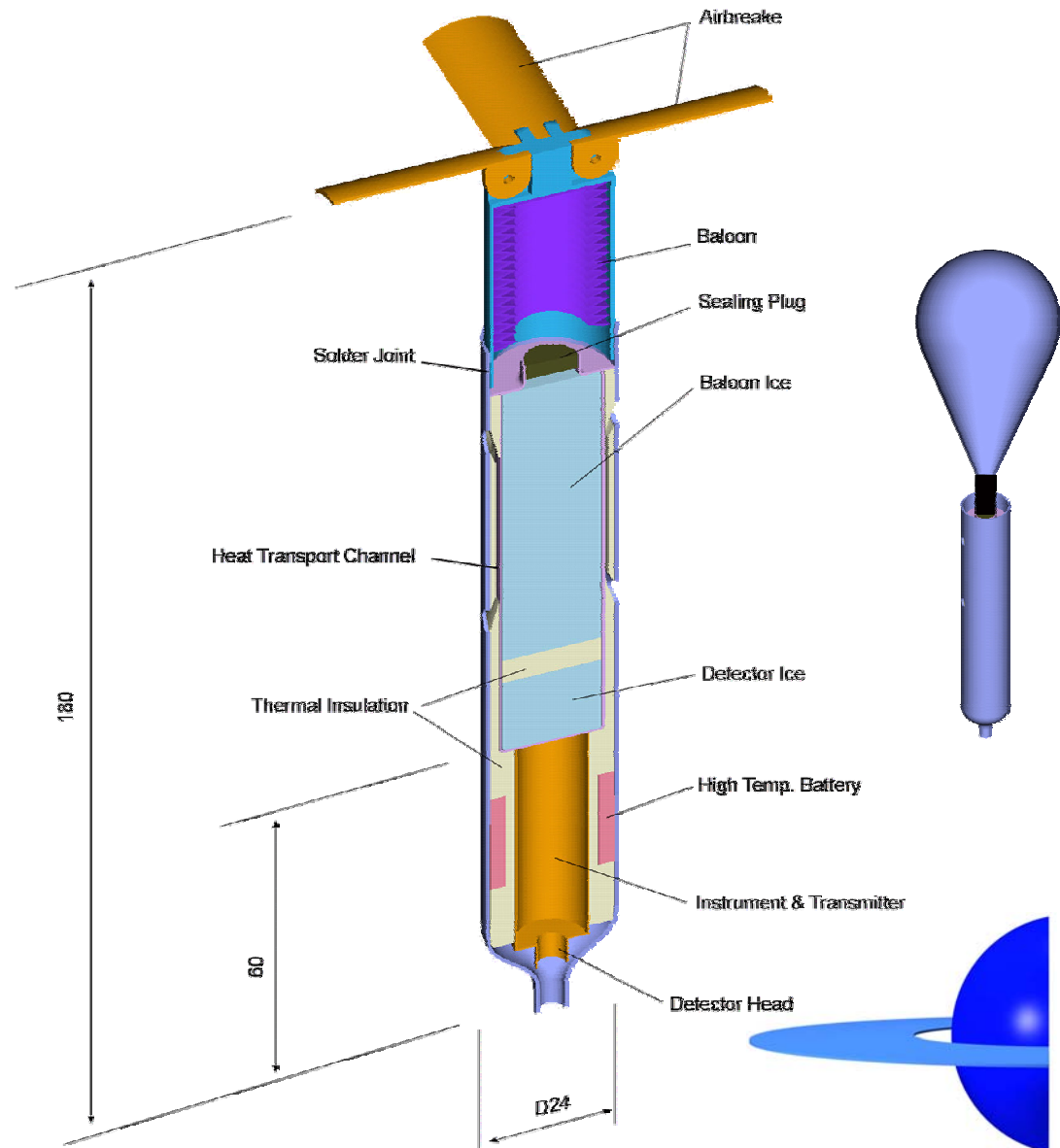


LOVECraft - Design



LOVECraft – Ballast probes

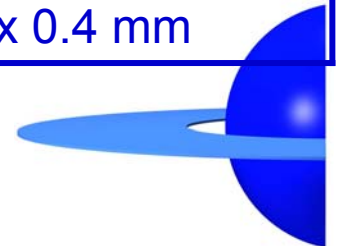
- Length: 180mm
- Diameter: 24mm
- Weight: 100g



How much electronics and mechanical functions can a MMS hold?

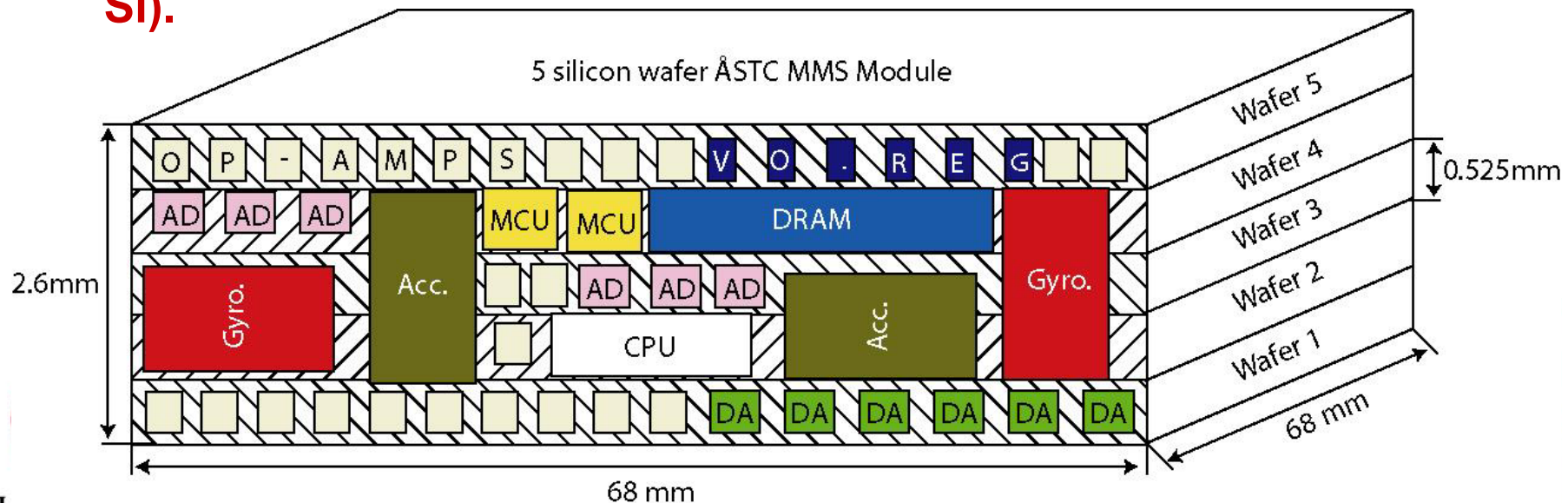
- Typical naked-die dimensions on some typical circuits;
- The thickness of typical dies are normally, 330um, 525um or less
- Let us look at a imaginary module consisting of:
12 ADC, 12 DAC, 50 OP AMPs, 8 Gbit DRAM, 2 CPU, 4 MCUs, 4 Gyros, 4 Accel., 6 Volt. reg., 40 diodes.

| Component | Die dimension |
|--------------------|-------------------|
| ADC (12-bit) | 2 x 3.3 mm |
| DAC (12-bit) | 2.9 x 2.8 mm |
| OP AMP | 1.9 x 2.4 mm |
| DRAM (4Gbit) | 23 x 23 mm |
| Volt. Switch reg. | 1.8 x 1.8 mm |
| MEMS Gyro | 7 x 7 mm (avg.) |
| MEMS Accel. | 7 x 7 mm (avg.) |
| CPU (AMD, PPC,...) | 13 x 13 mm (avg.) |
| uC, MCU | 3 x 3 mm (avg.) |
| Diode | 0.4 x 0.4 mm |



How much electronics and mechanical functions can a MMS module hold? (2)

- A typical ÅSTC MMS module consists of four to six 525um silicon wafers and have the dimension of 68 x 68 x 2.6 mm, example below is average with 5 wafers.
- Total volume of silicon that can be removed: 12020 mm³
- Volume of all selected components: 1510 mm³
- **13% of the volume is utilized for chips, weight: 25g (everything Si).**



How much electronics and mechanical functions can a MMS module hold? (3)

- Not included in previous 13% utilization of the module is
 - ◆ Supporting circuits such as resistors, capacitors, inductors, diodes
 - ◆ Internal conductors
 - ◆ Interconnection interface to another MMS module, or to macroscopic world.
 - ◆ Local radiation shields, typically of ~ 400um thickness or more
- All this together will typically fit into 45-55% of the total volume.

